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GE Industrial Systems

## Functional Testing Specification

*Renewal Services  
Louisville, KY*

**LOU-GED-193X390xx**

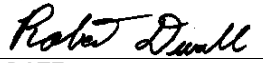
### Test Procedure for a 193X390AAG01

**DOCUMENT REVISION STATUS:** Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	Steve Pharris	08/08/02
B			
C			

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<b>DATE</b> 8/8/02	<b>DATE</b>	<b>DATE</b>	<b>DATE</b> 10/25/02

## Functional test procedure for 193X390AAG01

### 1. SCOPE

1.1 This is a functional testing procedure for a 193X390AAG01.

### 2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

### 3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1

### 4. ENGINEERING REQUIREMENTS

#### 4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.

#### 4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires broken or cracked

4.2.1.2 Terminal strips / connectors broken or cracked

4.2.1.3 Loose wires

4.2.1.4 Components visually damaged

4.2.1.5 Capacitors leaking

4.2.1.6 Solder joints damaged or cold

4.2.1.7 Circuit board burned or de-laminated

4.2.1.8 Printed wire runs burned or damaged

### 5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Power Supply
1		SCR Firing Box
1		O-Scope
1		BNC to Banana Jack Connector
1		100 Ohm Resistor

## 6. TESTING PROCESS

### 6.1 Setup

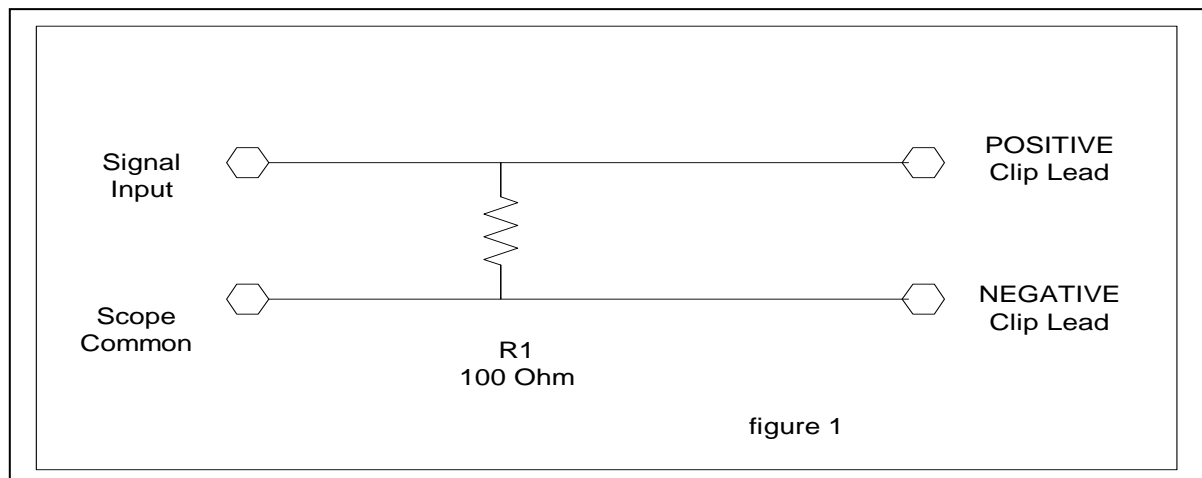
- 6.1.1 Set power supply for +20VDC.
- 6.1.2 Connect positive lead from +20VDC to pin labeled 20V on card.
- 6.1.3 Connect negative lead from +20VDC to pin labeled COM on card.
- 6.1.4 From the SCR firing box connect non isolated negative to pin labeled COM on card.
- 6.1.5 Place resistor in parallel with O-Scope input. (See notes.)

### 6.2 Testing Procedure

- 6.2.1 Connect positive lead from SCR firing box to pin labeled 1P.
- 6.2.2 Connect positive lead from scope to pin labeled 1PG.
- 6.2.3 Connect negative lead from scope to pin labeled 1PC.
- 6.2.4 Apply voltage from power supply, turn on SCR firing box in normal mode. Turn potentiometer on firing box fully CW.
- 6.2.5 Verify waveform in Fig. 1
- 6.2.6 Repeat steps 6.2.1 through 6.2.5 using table below for connections. (See notes)
- 6.2.7 If no deviations are found card passed.

### 6.3 **\*\*\*TEST COMPLETE \*\*\***

## 7. NOTES



SCR firing box Positive lead	O-scope Positive lead	O-scope Negative lead
1N	1NG	1NC
2P	2PG	2PC
2N	2NG	2NC

8. Oscilloscope Verification Examples:

Fig. 1

